



Material Content Data Sheet



Sales Product Name		IPD65R380C6		Issued		20. July 2018		
MA#		MA001039194						
Package		PG-TO252-3-341		Weight*		383.83 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.901	1.28	1.28	12768	12768
leadframe	non noble metal	iron	7439-89-6	0.248	0.06		647	
	inorganic material	phosphorus	7723-14-0	0.075	0.02		194	
	non noble metal	copper	7440-50-8	248.124	64.64	64.72	646446	647287
wire	non noble metal	aluminium	7429-90-5	4.438	1.16	1.16	11562	11562
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.650	0.43		4299	
	plastics	brominated resin	-	1.768	0.46		4606	
	organic material	carbon black	1333-86-4	1.886	0.49		4913	
	plastics	epoxy resin	-	15.912	4.15		41457	
	inorganic material	silicondioxide	60676-86-0	96.652	25.18	30.71	251812	307087
leadfinish	non noble metal	tin	7440-31-5	3.740	0.97	0.97	9744	9744
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1326	1326
solder	noble metal	silver	7440-22-4	0.098	0.03		256	
	non noble metal	tin	7440-31-5	0.078	0.02		205	
	non noble metal	lead	7439-92-1	3.748	0.98	1.03	9765	10226
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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